

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below, in clean form, for clarity.

Please amend the claims as follows:

1. (Previously Amended) An electronic device comprising:  
an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;  
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame formed by one of compression molding and injection molding;  
an adhesive attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;  
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of said plurality of lead fingers of said conductive plastic lead frame; and  
encapsulating material for encapsulating at least a portion of said integrated circuit semiconductor die and for encapsulating at least a portion of at least one lead of said conductive plastic lead frame.

3. (Previously Amended) An electronic device comprising:  
an integrated circuit semiconductor die having at least one bond pad thereon for attachment in one of a conventional die attach to lead frame connect process and a LOC connect process;  
a conductive plastic lead frame having a plurality of lead fingers, said conductive plastic lead frame including a plastic lead frame structure having a conductive polymeric material located on at least a portion of said plurality of lead fingers;  
an adhesive for attaching a portion of said integrated circuit semiconductor die to a portion of said conductive plastic lead frame;  
at least one connector connecting said at least one bond pad of said integrated circuit semiconductor die to at least one lead finger of said conductive plastic lead frame; and

encapsulating material for encapsulating at least a portion of said integrated circuit  
semiconductor die and for encapsulating at least a portion of said at least one lead of said  
conductive plastic lead frame.